

Job number: OCULUS 4 LAYER	Material: 370HR	<div>External</div> <div>Stackup Report</div> <div>Report v1.71</div>	
Part number: DK2, Rev: 3	Impedance: Yes		
Customer: OCULUS VR	Date: 29-Jan-2014		
Panel size: 18X24	Created by: A		

Layer	Type	CU Weight	CU %	Material Description	Via Structure	Segment	Glass Style	Material Family	Dielectric constant @ 1GHz	Thickness After lamination [mil]
Soldermask										0.80
1	Signal	H	26	Press thk = 4.85 mil		Foil	2116(57)	370HR	4.06	1.60
2	Mixed	1	91	24.0 mil 1/1		Prepreg	3-7628, 1-1080	370HR	4.32	4.85
3	Plane	1	88	Press thk = 4.83 mil		Core	2116(57)	370HR	4.06	1.20
4	Signal	H	11			Prepreg				24.00
Soldermask						Foil				1.20
										4.83
										1.60
										0.80

Specification (Over mask on plated copper):	mil
Overall Board Thickness:	40.0
Tolerance:	+4.0/-4.0
Min-Max Board Thickness:	36.0-44.0

Anticipated Board Thickness:	mil
After lamination:	37.27
Over mask on plated copper:	39.67

Grain in 18" Dimension

Impedance Table

InSolver

Layer	Impedance Requirement [ohms]	Tolerance [ohms]		Type	Upper Reference	Lower Ref	Designed Line Width [Mil]	Designed Spacing [Mil]	Finished Line Width [Mil]	Finished Spacing [Mil]	Impedance Simulation [ohms]
		+	-								
1	100	10	10	Differential		2	5.905	9.84	6.25	9.50	100.493
4	100	10	10	Differential		3	5.905	9.84	6.25	9.50	100.341

Remarks

PRELIMINARY STACK UP

* Any targeted thickness .0046" and greater shall have a minimum tolerance of +/- .001 after lamination.

* Any targeted thickness .0045" and below shall not be held to the minimum dielectric .0035429" as specified in IPC-6012 section 3.6.2.15. Unless agreed upon in writing. The minimum thickness per this exception shall not be less than .0009839" per IPC-6012 section 3.6.2.15.